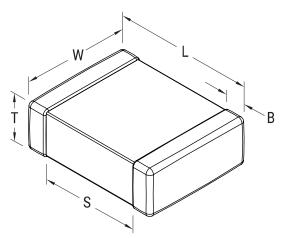


C0603T101K5GCLTU

Aliases (C0603T101K5GCL7867) SMD COTS C0G, Ceramic, 100 pF, 10%, 50 VDC, C0G, SMD, MLCC, COTS, Ultra-Stable, Low Loss, Class I, 0603, 0.5 mm



Click here for the 3D model.

SeriesSMD COTS COGStyleSMD ChipDescriptionSMD, MLCC, COTS, Ultra-Stat Low Loss, Class IFeaturesUltra-Stable, Low Loss, ClassRoHSNoProp 65WARNING: Cancer and reproductive harm - https://www.p65warnings.ca. /SCIP Number2d771165-5336-48a3-96fa-3 3929fd828TerminationLead (SnPb)MarkingNoFailure RateTesting per MIL-PRF-55681 P 8%, DPA per EIA-469, Humid per MIL-STD-202, Method 10 Condition A	
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8%, DPA per EIA-469, Humid per MIL-STD-202, Method 10	
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AEC-Q200 No	
Typical Component Weight 3.7 mg	
Shelf Life 78 Weeks	
MSL 1	

Dimensions	
Chip Size	0603
L	1.6mm +/-0.15mm
W	0.8mm +/-0.15mm
т	0.8mm +/-0.07mm
S	0.5mm MIN
В	0.35mm +/-0.15mm

Packaging Specifications	
Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

Specifications	
Capacitance	100 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	10%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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